

4

3

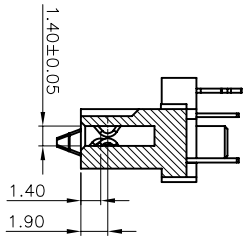
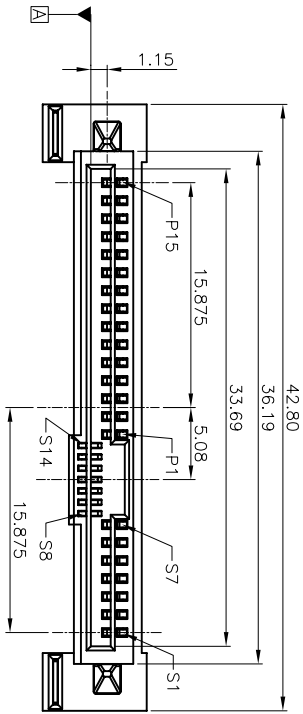
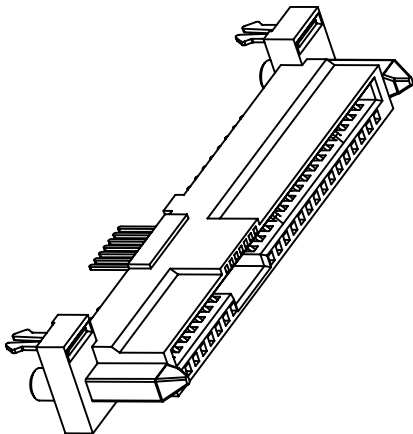
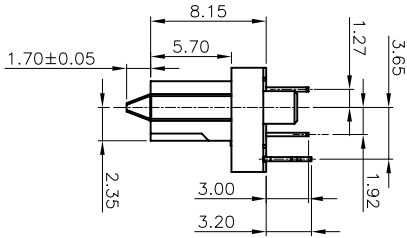
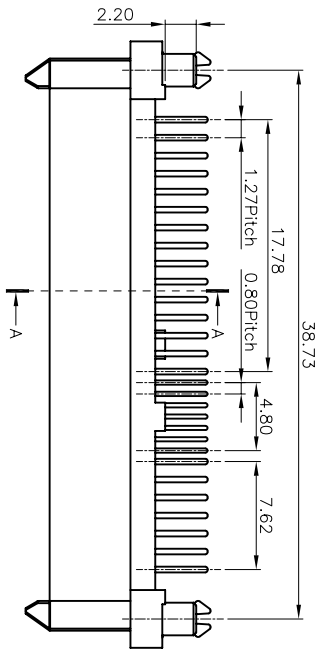
2

1

PART NO. SEE TABLE 1

CUSTOMER
DRAWING

REVISIONS			
LTR	DESCRIPTION	Drawing	DATE
B	Initial Release for Manufacture	Marcy	03/08/06



RECOMMENDED PCB LAYOUT

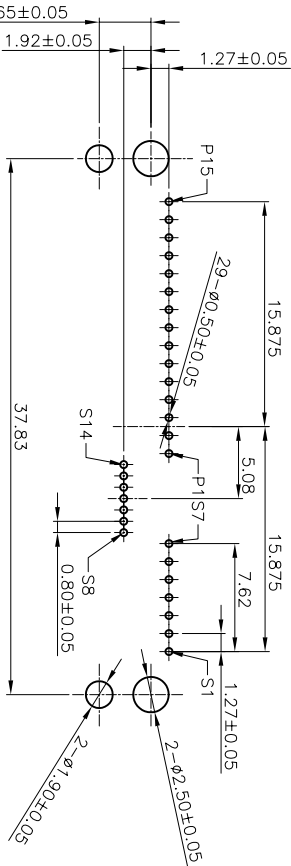


TABLE 1

XXXXXXXXXXXX	15 U" GOLD	NY9T BLACK
XXXXXXXXXXXX	GOLD FLASH	NY9T BLACK
PART NO.	PLATED	COLOR FOR THE PLASTIC

NO	DESCRIPTION		QTY	UNIT	DO NOT SCALE DRAWING	ID NO.	
						XXXXXXXXXX	SHEET 1 OF 1

NOTE:
1.MATERIAL :
HOUSING : High Temperature thermoplastic ,
UL94V-0, COLOR : BLACK
TERMINAL(max):Copper alloy,THICKNESS = 0.30 mm
TERMINAL(min):Copper alloy,THICKNESS = 0.25 mm
FORKLOCK: Copper alloy,THICKNESS = 0.30 mm
2.PLATING:
CONTACT:GOLD OVER 50u" MIN NICKEL UNDERPLATE(SEE TABLE1)
SOLDER TAIL:.75u"MIN TIN 50u" MIN NICKEL UNDERPLATE
GOLD SPECIFICATION:
a, Flash: b, 15u", c, 30u";
3.ELECTRONICAL SPECIFICATION:
CURRENT RATING:1.5 AMPERE PER CONTACT
CONTACT RESISTANCE:30 MILLIOHMS MAX.
INSULATION RESISTANCE:1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING VOLTAGE:500 VAC.
OPERATING TEMPERATURE:-55C° ~+125C°

E-GREEN

TITLE:
ASSEMBLY OF SAS 29P Vertical DIP(2 ROW)

APPROVALS		DATE
DRAWN	Marcy	03/08/06
CHECKED		
APPROVALS		

SIZE	SCALE:	DRAWING NO.	REV.
mm	1 : 1		B
ID NO.	XXXXXXXXXX		